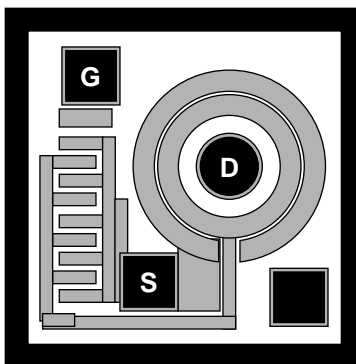


LND1



Backside: Source <sup>4</sup>

All dimensions in mils.

Die Geometry	Dimensions			Backside Metal	Bonding Pads <sup>2</sup>		Recommended Assembly Material		
	Length <sup>1</sup>	Width <sup>1</sup>	Thickness		Material	Size	Wire <sup>3</sup>	Wire Size <sup>3</sup>	Preform
LND1	30	30	11 ± 1.5	None	Al-Cu-Si	3.8 x 3.8	Au	1.0	Epoxy

**Notes:**

1. Maximum values
2. Bond sizes are for source and gate pads.
3. Bond wire size and material depends on AuTCB, TSB or Al USB.
4. Source pad bonding is required.

11/19/02